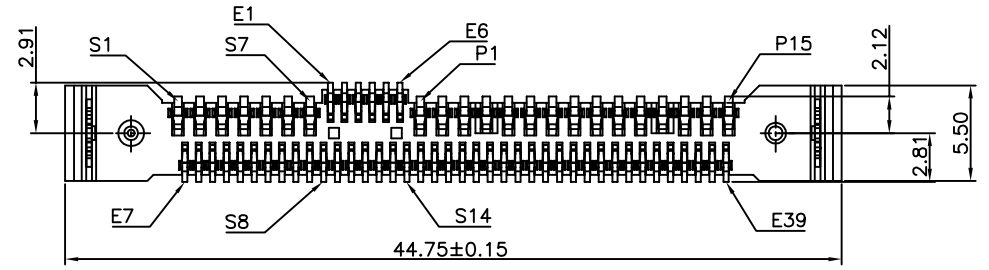
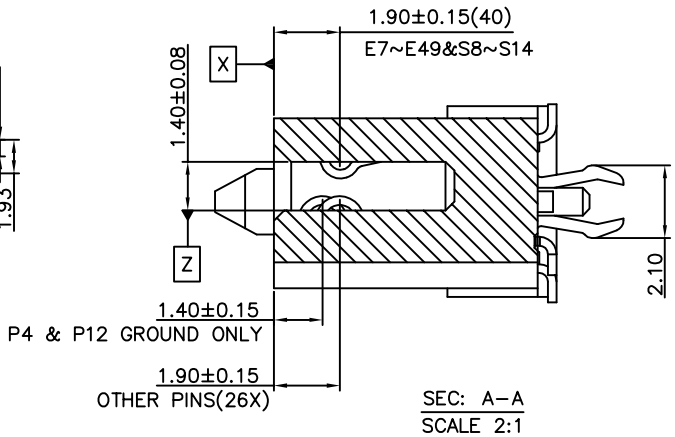
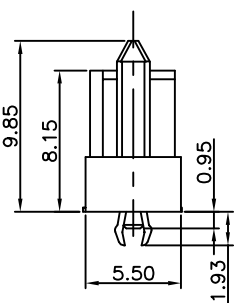
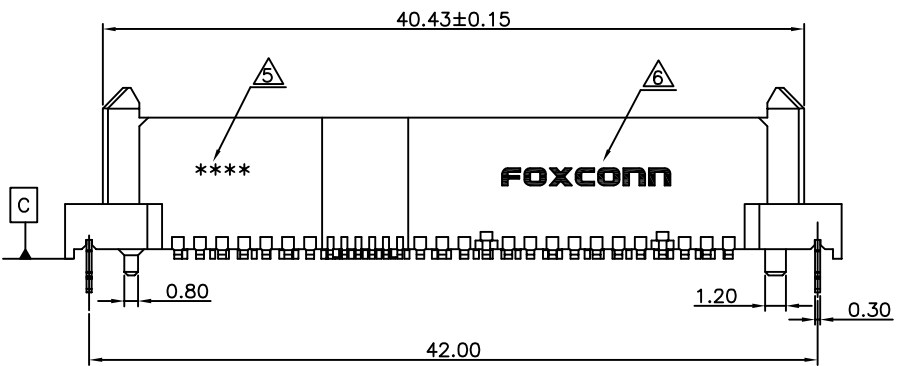
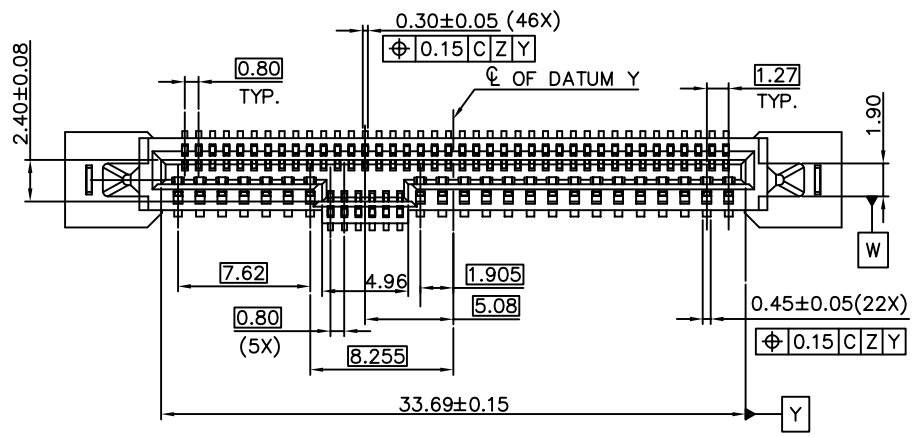


REV.	ECN. No.	APPD.
A	BC-11-0043665	Yihsin Chen
B	BC-12-0035993	Shin-Wei Hsiao

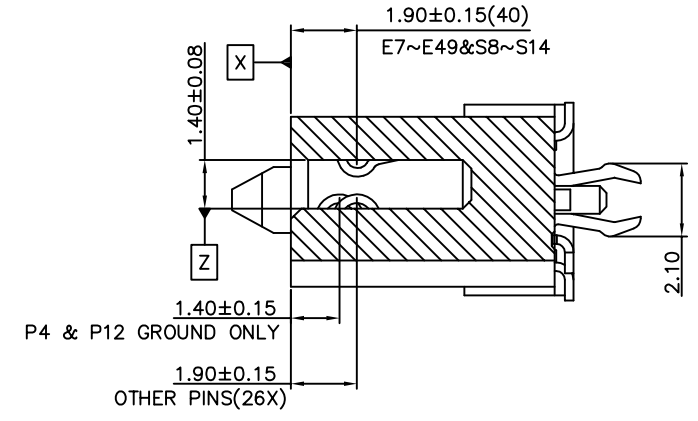
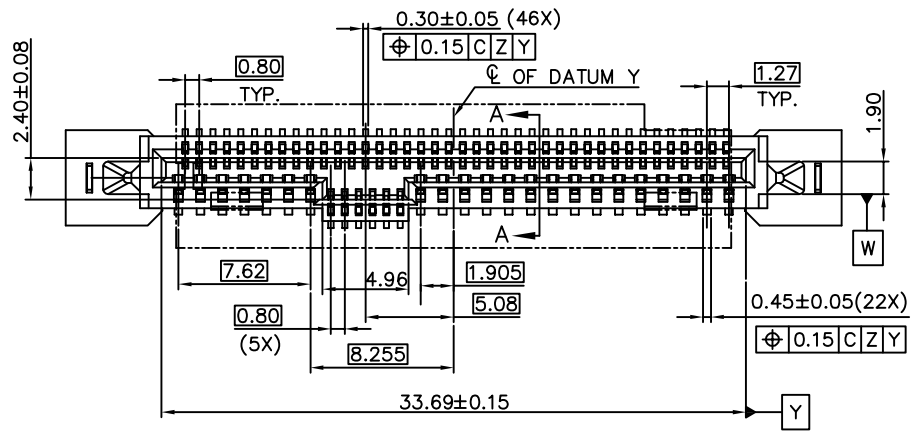
NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS SHALL BE INTERPRETED PER ASME Y14.5-2009
2. DIMENSIONS MARKED ∇ TO BE CONTROLLED BY QC.
3. CONTACT RETENTION FORCE : 0.3 KG MIN. PER PIN.
4. HARMFUL MATERIAL CONTROL PLEASE FOLLOW FOXCONN'S DOC. "EPI12".
5. DATE CODE: PLEASE REFER TO FOXCONN'S DOC. "SQ-3B0-070".
6. THE "FOXCONN" LOGO IS LOCATED APPROX. AS SHOWN.
7. SPEC. OF PROD. ARE SHOWN ON DRAWING 303-0300-2784
8. MATERIALS OF PARTS ARE SHOWN ON PRODUCT NO. MATRIX
9. THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOCUMENT EPI12.
10. PRODUCT No. MATRIX :

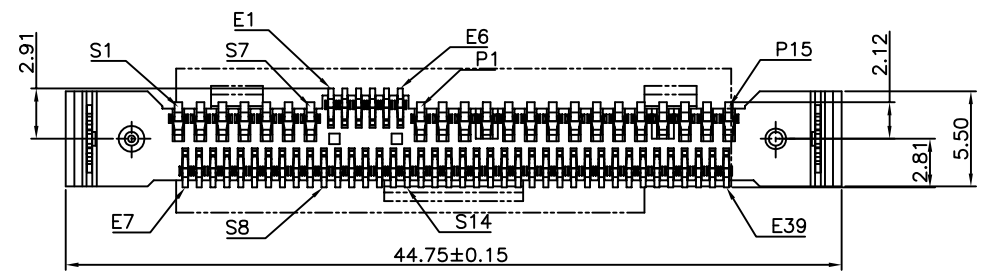
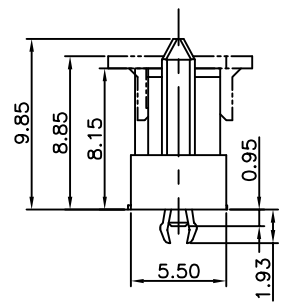
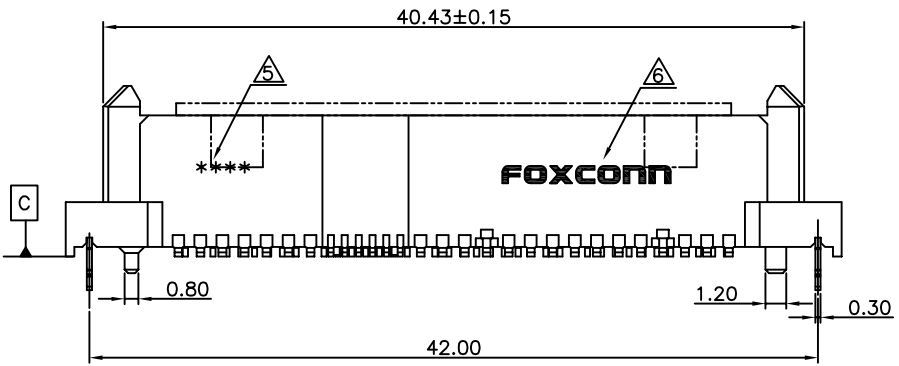
LU 2 5 68 * - A 0 0 1 - * H
 DEVICE BAY & SERIAL ATA
 MATING END TYPE 2 = RECEPTACLE
 MOUNTING END TYPE 5=VERTICAL,SMT
 NO. OF POS. 68 = 68 POS.
 H=HALOGEN FREE
 PACKAGE TYPE: 4= SOFT TRAY
 9= TAPE REEL & CAP
 DEVELOP SERIES NO: (0,1,2,...)
 CONTACT AREA PLATING:
 1 = GOLD FLASH WITH RoHS COMPLIANT
 3 = 30u" GOLD WITH RoHS COMPLIANT
 6 = 10u" GOLD WITH RoHS COMPLIANT
 7 = 15u" GOLD WITH RoHS COMPLIANT



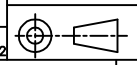
X.±		X'.±	UNITS mm	NAME(INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.
.X± 0.20		.X'±	MAT'L	PCI-e SAS	
.XX± 0.15		.XX'±	FINISH	PART NO.(INTENDED USE)	TITLE:
.XXX± 0.10		.XXX'±		LU2568*-A001-*H	APPD: Shin-Wei Hsiao
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.			Q'TY	CHKD: Yusan Hsiao	DWG NO.:
				DR: Zou Jianlong 5/10/12	303-0000-2784
				SCALE	SHEET
				1:1	1/4
				REV.	B

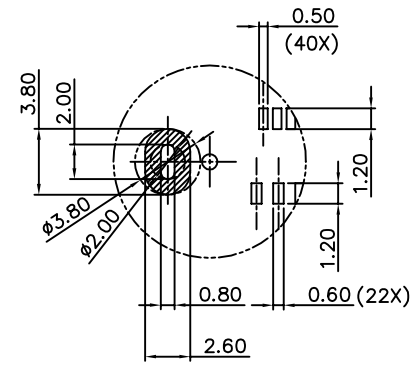
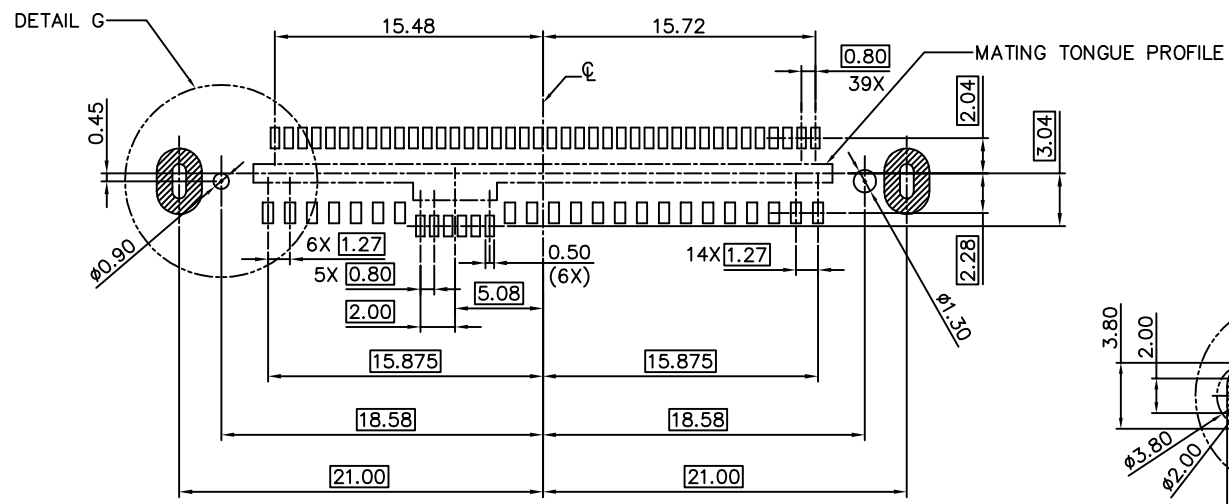


SEC: A-A
SCALE 2:1



X.±		X'.±	UNITS	mm	NAME(INTENDED USE)	P/N	LU2568*-A001-9H	
.X± 0.20		.X'±	MAT'L		PCI-e SAS	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.		
.XX± 0.15		.XX'±			PART NO.(INTENDED USE)	TITLE: CUSTOMER DRAWING V/T, SMT, RECEPTACLE		
.XXX± 0.10		.XXX'±	FINISH		LU2568*-A001-*H	DWG NO.: 303-0000-2784		
<small>THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.</small>					APPD:	Shin-Wei Hsiao		
					CHKD:	Yusan Hsiao		
					DR:	Zou Jianlong 5/10/12		
			Q'TY			SCALE	SHEET	REV.
						1:1	2/4	B

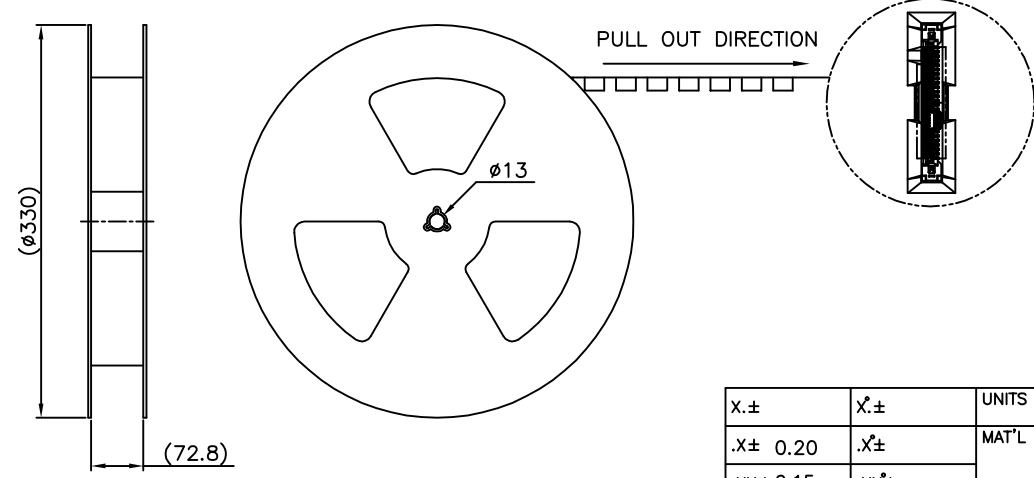
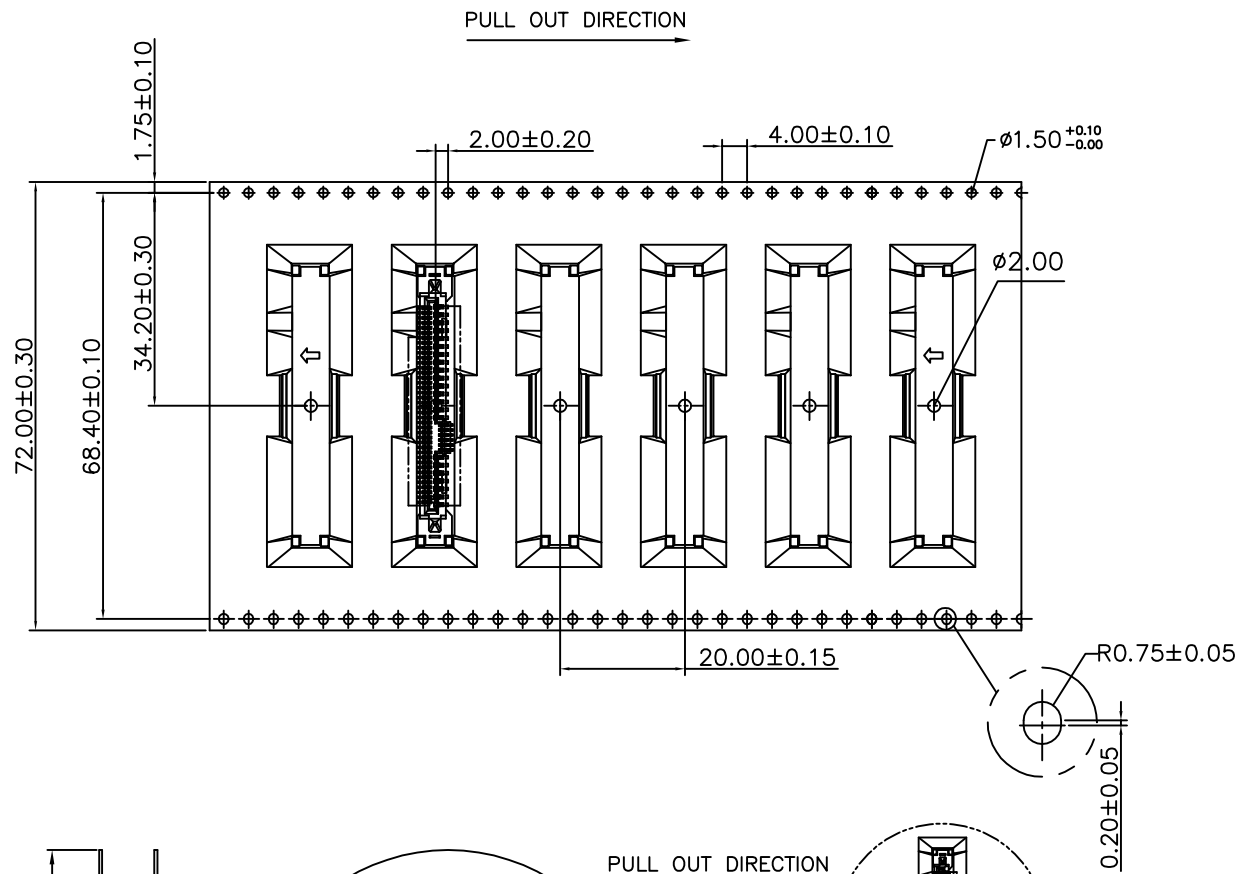




RECOMMENDED P.C.B. LAYOUT

DETAIL G

X.±	X'.±	UNITS	mm	NAME(INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.	
.X± 0.20	.X'±	MAT'L		PCI-e SAS		
.XX± 0.15	.XX'±			PART NO.(INTENDED USE)	TITLE: CUSTOMER DRAWING V/T, SMT, RECEPTACLE	
.XXX± 0.10	.XXX'±	FINISH		LU2568*-A001-*H	DWG NO.: 303-0000-2784	
THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.				APPD: Shin-Wei Hsiao		
				Q'TY	CHKD: Yusan Hsiao	
					DR: Zou Jianlong 5/10/12	
					SCALE SHEET REV. 1:1 3/4 B	



X.±	X'.±	UNITS	mm	NAME(INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.
.X± 0.20	.X'±	MAT'L		PCI-e SAS	
.XX± 0.15	.XX'±			PART NO.(INTENDED USE)	TITLE: CUSTOMER DRAWING V/T, SMT, RECEPTACLE
.XXX± 0.10	.XXX'±	FINISH		LU2568*-A001-*H	DWG NO.: 303-0000-2784
<small>THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF HON HAI PRECISION IND. CO., LTD. AND SHALL NOT BE REPRODUCED, COPIED OR USED IN ANY MANNER WITHOUT THE PRIOR WRITTEN CONSENT OF HON HAI PRECISION IND. CO., LTD.</small>				APPD: Shin-Wei Hsiao	
				CHKD: Yusan Hsiao	
				DR: Zou Jianlong 5/10/12	
					SCALE SHEET REV. 1:1 4/4 B

SPECIFICATIONS :

1. MATERIAL AND FINISH :

1-1. HOUSING :

HIGH TEMP. THERMOPLASTIC, UL94V-0 , COLOR BLACK.

1-2. CAP :

HIGH TEMP. THERMOPLASTIC, UL94V-0 , COLOR BLACK.

1-3. S-ATA CONTACT :

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u" MIN.
MATTE-TIN PLATING OVER NICKEL, THICKNESS 100u" MIN. ON SOLDER AREA,
GOLD PLATING OVER NICKEL ON CONTACT AREA,

1-4. SAS CONTACT :

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u" MIN.
MATTE-TIN PLATING OVER NICKEL, THICKNESS 100u" MIN. ON SOLDER AREA,
GOLD PLATING OVER NICKEL ON CONTACT AREA,

1-5. PCI-e SAS PIN

COPPER ALLOY, 0.25mm THICK. NICKEL PLATING OVER ALL, THICKNESS 50u"MIN.
MATTE-TIN PLATING OVER NICKEL, ON SOLDER AREA, THICKNESS 100u" MIN.
GOLD PLATING OVER NICKEL ON CONTACT AREA,

1-6. BOARD LOCK:

COPPER ALLOY, NICKEL PLATING OVER ALL, THICKNESS 50u" MIN.,
MATTE-TIN PLATING OVER ALL, THICKNESS 100u"MIN..

1-7. HARMFUL MATERIAL CONTROL PLAESE FOLLOW DOC. NO."EPI12"

1-8. THE CONCENTRATIONS OF Br&Cl CAN SATISFYTHE REQUIREMENTS OF HALOGEN-FREE IN DOC. EPI12.

2. ELECTRICAL :

2-1. LOW LEVEL CONTACT RESISTANCE : 30 MILLIOHMS MAX. INITIAL.

2-2. DIELECTRIC WITHSTANDING VOLTAGE : EIA-364-20, NO BREAKDOWN.

2-3. INSULATION RESISTANCE : EIA-364-21, 1000 MEGAOHMS MIN.

2-4. TEMPERATURE RISE(VIA CURRENT CYCLING) POWER SECTION ONLY
(P1 THROUGH P15) : THE TEMPERATURE RISE SHALL NOT EXCEED 30°C.

3. MECHANICAL:

3-1. MATING FORCE: EIA-364-13, 25N MAX.

3-2. UNMATING FORCE: EIA-364-13, 4.5N MIN. INITIAL AND AFTER DURABILITY

3-3. DURABILITY: 500 CYCLES

3-4. PHYSICAL SHOCK: PASS EIA-364-27, CONDITION H.

3-5. VIBRATION: PASS EIA-364-28, CONDITION VII TEST LETTER A.

4. ENVIRONMENTAL:

4-1. HUMIDITY: PASS EIA-364-31, METHOD II TEST CONDITION A.

4-2. OPERATING TEMPERATURE: -55° TO +85°.

4-3. TEMPERATURE LIFT:PASS EIA-364-17,TEST CONDITION III, METHOD A

4-4. MIXED FLOWING GAS:PASS EIA-364-65, CLASS 2A.

FOXCONN

HON HAI PRECISION IND. CO.,LTD.
TAIPEI, TAIWAN, R.O.C.

APPD. :
Shih-Wei Hsiao

TITLE : SPECIFICATION SHEET
PCI-e SAS 68 PIN REC. V/T SMT

CHKD. :
Yusan Hsiao

PROD. SERIES: LU2568*-A00*-*H

DR. : Zou Jianlong
5/11'12

DWG. NO : 303-0300-2784

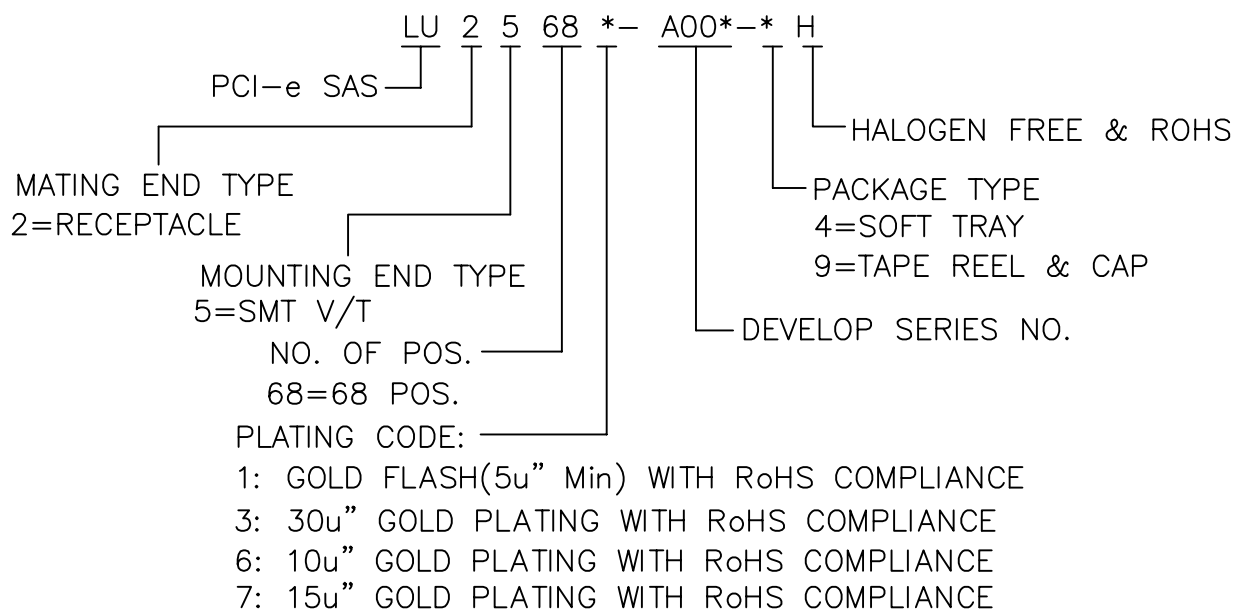
REV. : B

SHEET : 1/1

B	BC-12-0035506	Shih-Wei Hsiao
A	BC-11-0043693	Yihsin Chen
REV.	ECN NO.	APPD.

ITEM	DESC.	Q'TY	MATERIAL	TREATMENT	REMARK
1	HOUSING	1	HIGH TEMPERATURE THERMO-PLASTIC, UL 94V-0	INJECTION MOLDING	
2	CAP	1	HIGH TEMPERATURE THERMO-PLASTIC, UL 94V-0	INJECTION MOLDING	
3	SATA PIN	22	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100 u" MIN ON SOLDER AREA C) GOLD PLATING OVER NICKEL. ON CONTACT AREA	
4	SAS PIN & PCI-e PIN	46	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50 u" MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100 u" MIN ON SOLDER AREA C) GOLD PLATING OVER NICKEL. ON CONTACT AREA	
5	BOARD LOCK	2	COPPER ALLOY	A) NICKEL PLATING OVER ALL THICKNESS : 50u"MIN. B) MATTE-TIN PLATING OVER NICKEL. THICKNESS : 100u"MIN ON SOLDER AREA	

- NOTE : 1. HARMFUL MATERIAL CONTROL PLEASE FOLLOW DOC. NO. "EPI12"
2. THE CONCENTRATIONS OF Br&Cl CAN SATISFY THE REQUIREMENTS OF HALOGEN-FREE IN DOC. EPI12.
3. PRODUCT NO. MATRIX:



4. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS&AVAILABILITY.

FOXCONN

HON HAI PRECISION IND. CO.,LTD.
TAIPEI, TAIWAN, R.O.C.

APPD. :
Shih-Wei Hsiao

TITLE :
MATERIAL SHEET
PCI-e SAS 68 PIN REC. V/T SMT

CHKD. :
Yusan Hsiao

PROD. SERIES : LU2568*-A00*-*H

DR. :
Zou Jianlong
5/11'12

DWG. NO : 303-0500-2784

REV. : B

SHEET : 1/1

B	BC-12-0035653	Shih-Wei Hsiao
A	BC-11-0043656	Yihsin Chen
REV.	ECN NO	APPD.